A, W, H, McL & N Docket No.

h For U.S. Patent Appli

As a below named inventor, I hereby declare that:

My residence,	post office address a	nd citizenship are as stated	below next to my name.
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•	fice address and citizenship are as stated			
I believe I am the orig names are listed below (Insert Title)	ginal, first and sole inventor (if only one w) of the subject matter which is claimed	name is listed below) or d and for which a patent	is sought on the invention entitle	
	ONDUCTIVE LAYERED STRUCTURE AND METHOD ATING LIQUID FOR FORMING TRANSPARENT C	OF PRODUCING THE SAME, CONDUCTIVE LAYER USED IN	COATING LIQUID FOR FORMING TRA	NSPARENT COATING CONDUCTIVE LAYEREI
STRUCTURE, AN	D DISPLAY THAT USES TRANSPARENT CONDUC	TIVE LAYERED STRUCTURE		
the specification of w	hich is attached hereto unless the follow	ring is checked:	•	
was	filed on	as Unite	d States Application Number or l	PCT International
App	olication Number		and was amended on	
(if a	applicable).			
I hereby state that I hat by any amendment re	ave reviewed and understand the content ferred to above.	ts of the above-identified	specification, including the clair	n(s), as amended
I hereby claim foreigr inventor's certificate l	y to disclose information which is material priority benefits under Title 35, United listed below and have also identified belof the application on which priority is claim	States Code, § 119 (a) - ow any foreign application	(d) of any foreign application(s)	for patent or
	239771/1999	JAPAN	26/8/1999	Priority Claimed
(List prior foreign	(Number) 041887/2000	(Country) JAPAN	(Day/Month/Year Filed) 18/2/2000	_ XO Yes O No
applications. See note A	(Number) 187580/2000	(Country) JAPAN	(Day/Month/Year Filed) 22/6/2000	_ _ X⊡ Yes □ No
on back of this page)	(Number)	(Country)	(Day/Month/Year Filed)	☐ Yes ☐ No
T.	(Number)	(Country)	(Day/Month/Year Filed)	
(See note B on back of	of this page)	list for additional prior f	oreign applications	
I hereby claim the ber	nefit under Title 35, United States Code,	§ 119(e) of any United S	States provisional application(s) l	isted below.
	(Application Number)		(Filing Date)	_
•	(Application Number)		(Filing Date)	_
subject matter of each the first paragraph of ity as defined in Title	nefit under Title 35, United States Code, of the claims of this application is not of Title 35, United States Code, § 112, I ac 37, Code of Federal Regulations, § 1.56 CT international filing date of the applications.	disclosed in the prior Uni- knowledge the duty to dis which became available	ited States application in the man isclose information which is mate	erial to patentabil-
(List Prior U.S. Applications)	(Application Serial Number)	(Filing Date)	(Status) (patented, pendin	
	(Application Serial Number)	(Filing Date)	(Status) (patented, pending	ig, abandoned)
	ollowing attorney(s) and/or agent(s) to p	prosecute this application	and to transact all business in the	e Patent and

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I hereby declare that all statements mad herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Title 18 of the United States Code, § 1001 and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

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